捷多邦,专业PCB打样工厂CD54A01635CD74AC163 4-BIT SYNCHRONOUS BINARY COUNTERS

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- Internal Look-Ahead for Fast Counting
- Carry Output for n-Bit Cascading
- Synchronous Counting
- Synchronously Programmable
- Package Options Include Plastic Small-Outline (M), Standard Plastic (E) and Ceramic (F) DIPs

description

The CD54AC163 and CD74AC163 devices are 4-bit binary counters. These synchronous, presettable counters feature an internal carry look-ahead for application in high-speed counting

CD54AC163 . . . F PACKAGE CD74AC163 . . . E OR M PACKAGE (TOP VIEW) CLR 16 VCC CLK [15 RCO 14 QA A в 13 Q_B сΠ 12 Q_C 11 🛮 Q_D DΓ 6 ENP ∏ 7 10 | ENT GND [9 LOAD

designs. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincident with each other when instructed by the count-enable (ENP, ENT) inputs and internal gating. This mode of operation eliminates the output counting spikes normally associated with synchronous (ripple-clock) counters. A buffered clock (CLK) input triggers the four flip-flops on the rising (positive-going) edge of the clock waveform.

The counters are fully programmable; that is, they can be preset to any number between 0 and 9 or 15. Presetting is synchronous; therefore, setting up a low level at the load input disables the counter and causes the outputs to agree with the setup data after the next clock pulse, regardless of the levels of the enable inputs.

The clear function is synchronous. A low level at the clear ($\overline{\text{CLR}}$) input sets all four of the flip-flop outputs low after the next low-to-high transition of CLK, regardless of the levels of the enable inputs. This synchronous clear allows the count length to be modified easily by decoding the Q outputs for the maximum count desired. The active-low output of the gate used for decoding is connected to $\overline{\text{CLR}}$ to synchronously clear the counter to 0000 (LLLL).

The carry look-ahead circuitry provides for cascading counters for n-bit synchronous applications without additional gating. ENP, ENT, and a ripple-carry output (RCO) are instrumental in accomplishing this function. Both ENP and ENT must be high to count, and ENT is fed forward to enable RCO. Enabling RCO produces a high-level pulse while the count is maximum (9 or 15 with Q_A high). This high-level overflow ripple-carry pulse can be used to enable successive cascaded stages. Transitions at ENP or ENT are allowed, regardless of the level of CLK.

These devices feature a fully independent clock circuit. Changes at control inputs (ENP, ENT, or LOAD) that modify the operating mode have no effect on the contents of the counter until clocking occurs. The function of the counter (whether enabled, disabled, loading, or counting) is dictated solely by the conditions meeting the stable setup and hold times.

The CD54AC163 is characterized for operation over the full military temperature range of –55°C to 125°C. The CD74AC163 is characterized for operation from –40°C to 85°C.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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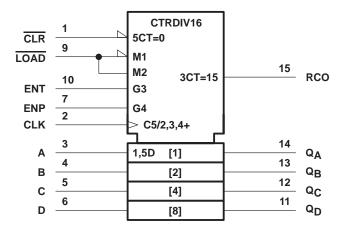
FUNCTION TABLE

		IN	IPUTS			OUTPUTS		FUNCTION
CLR	CLK	ENP	ENT	LOAD	A,B,C,D	Qn	RCO	FUNCTION
L	1	Χ	Χ	Χ	Χ	L	L	Reset (clear)
h	1	Χ	Χ	I	I	L	L	Parallel load
h	\uparrow	X	Χ	I	h	Н	Note 1	Parallel load
h	1	h	h	h	Χ	Count	Note 1	Count
h	Х	- 1	Χ	h	Χ	qn	Note 1	Inhibit
h	Χ	Χ	1	h	Χ	qn	L	ITITIDIL

H = high level, L = low level, X = don't care, h = high level one setup time prior to the CLK low-to-high transition, I = low level one setup time prior to the CLK low-to-high transition, q = the state of the referenced output prior to the CLK low-to-high transition, \uparrow = CLK low-to-high transition.

NOTE 1: The RCO output is high when ENT is high and the counter is at terminal count (HHHH).

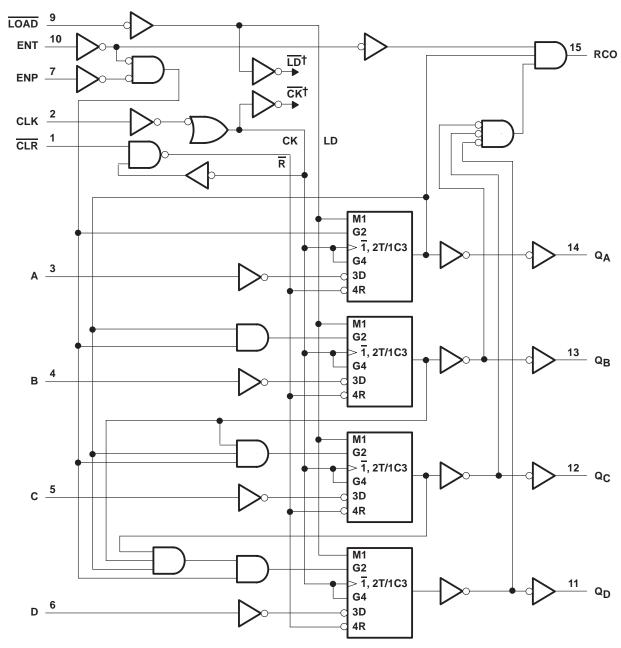
logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)

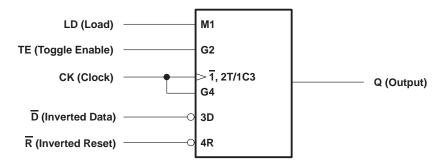


[†] For simplicity, routing of complementary signals \overline{LD} and \overline{CK} is not shown on this overall logic diagram. The uses of these signals are shown on the logic diagram of the D/T flip-flops.

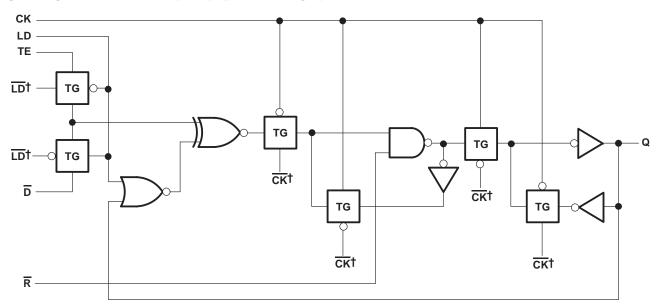


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logic symbol, each D/T flip-flop



logic diagram, each D/T flip-flop (positive logic)



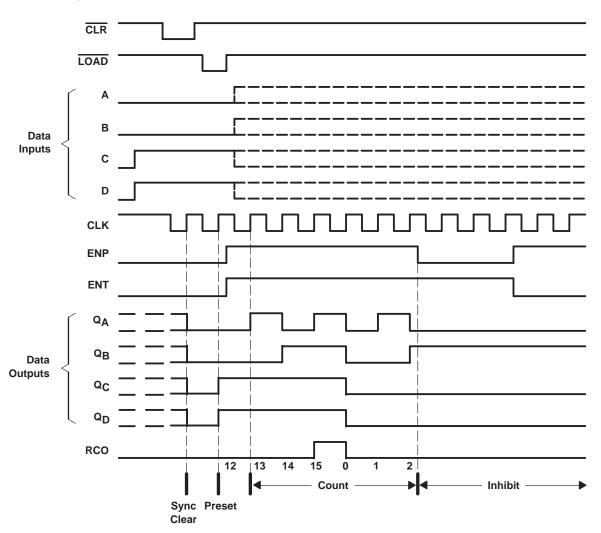
 $[\]dagger$ The origins of $\overline{\text{LD}}$ and $\overline{\text{CK}}$ are shown in the logic diagram of the overall device.



typical clear, preset, count, and inhibit sequence

The following sequence is illustrated below:

- 1. Clear outputs to zero (synchronous)
- 2. Preset to binary 12
- 3. Count to 13, 14, 15, 0, 1, and 2
- 4. Inhibit





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absolute maximum ratings over operating free-air temperature range†

Supply voltage range, V _{CC}	–0.5 V to 6 V
Input clamp current, I _{IK} (V _I < 0 or V _I > V _{CC}) (see Note 2)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 2)	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V _{CC} or GND	
Package thermal impedance, θ _{JA} (see Note 3): E package	
M package	
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 2. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

			T _A = 25°C		CD54AC163		CD74AC163		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	UNII
VCC	Supply voltage		1.5	5.5	1.5	5.5	1.5	5.5	V
		V _{CC} = 1.5 V	1.2		1.2		1.2		
V_{IH}	High-level input voltage	V _{CC} = 3 V	2.1		2.1		2.1		V
		V _{CC} = 5.5 V	3.85		3.85		3.85		
VIL	Low-level input voltage	V _{CC} = 1.5 V		0.3		0.3		0.3	V
		V _{CC} = 3 V		0.9		0.9		0.9	
		V _{CC} = 5.5 V		1.65		1.65		1.65	
٧ _I	Input voltage		0	VCC	0	VCC	0	VCC	V
٧o	Output voltage		0	VCC	0	Vcc	0	VCC	V
loh	High-level output current			-24		-24		-24	mA
lOL	Low-level output current			24		24		24	mA
Δt/Δν	land the critical rice on fall rate	$V_{CC} = 1.5 \text{ V to } 3 \text{ V}$	0	50	0	50	0	50	ne
ΔυΔν	Input transition rise or fall rate	$V_{CC} = 3.6 \text{ V to } 5.5 \text{ V}$	0	20	0	20	0	20	ns
T _A	Operating free-air temperature				- 55	125	- 40	85	°C
	·	· ·							

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	PARAMETER TEST CONDITIONS		V	T _A = 2	25°C	CD54AC163		CD74AC163		UNIT
PARAMETER			Vcc		MAX	MIN	MAX	MIN	MAX	UNIT
			1.5 V	1.4		1.4		1.4		
		I _{OH} = -50 μA	3 V	2.9		2.9		2.9		
			4.5 V	4.4		4.4		4.4		
Voн	VI = VIH or VIL	I _{OH} = -4 mA	3 V	2.58		2.4		2.48		V
		I _{OH} = -24 mA	4.5 V	3.94		3.7		3.8		
		$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V	_		3.85		_		
		$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V	_		_		3.85		
	VI = VIH or VIL	Ι _{ΟL} = 50 μΑ	1.5 V		0.1		0.1		0.1	
			3 V		0.1		0.1		0.1	
			4.5 V		0.1		0.1		0.1	
VOL		I _{OL} = 12 mA	3 V		0.36		0.5		0.44	V
		I _{OL} = 24 mA	4.5 V		0.36		0.5		0.44	
		I _{OL} = 50 mA†	5.5 V		-		1.65		_	
		I _{OL} = 75 mA†	5.5 V		-		-		1.65	
lį	$V_I = V_{CC}$ or GND		5.5 V		±0.1		±1		±1	μΑ
Icc	$V_I = V_{CC}$ or GND,	IO = 0	5.5 V		8		160		80	μΑ
Ci					10		10		10	pF

[†] Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.



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timing requirements over recommended operating free-air temperature range (unless otherwise noted)

				CD54A	C163	CD74A	C163	
			VCC	MIN	MAX	MIN	MAX	UNIT
			1.5 V		7		8	
fclock	Clock frequency		3.3 V ± 0.3 V		64		73	MHz
		5 V ± 0.5 V		90		103		
			1.5 V	69		61		ns
t _W	Pulse duration	CLK high or low	$3.3~V \pm 0.3~V$	7.7		6.8		
			5 V ± 0.5 V	5.5		4.8		
			1.5 V	63		55		
		A, B, C, or D	3.3 V ± 0.3 V	7		6.1		
			5 V ± 0.5 V	5		4.4		
		ENP or ENT	1.5 V	63		55		
	Setup time, before CLK↑		3.3 V ± 0.3 V	9.6		8.2		
۱.			5 V ± 0.5 V	5		4.4		
t _{su}		LOAD low	1.5 V	75		66		ns
			3.3 V ± 0.3 V	8.4		7.4		
			5 V ± 0.5 V	6		5.3		
		CLR inactive	1.5 V	75		66		
			3.3 V ± 0.3 V	8.4		7.4		
			5 V ± 0.5 V	6		5.3		
		A, B, C, or D	1.5 V	0		0		
			3.3 V ± 0.3 V	0		0		
			5 V ± 0.5 V	0		0		
1		ENP or ENT	1.5 V	0		0		
1			3.3 V ± 0.3 V	0		0		
	Uald time a after CLV↑		5 V ± 0.5 V	0		0		
th	Hold time, after CLK↑		1.5 V	0		0		ns
		LOAD low	3.3 V ± 0.3 V	0		0		
			5 V ± 0.5 V	0		0		
		CLR inactive	1.5 V	0		0		
			3.3 V ± 0.3 V	0		0		
			5 V ± 0.5 V	0		0		

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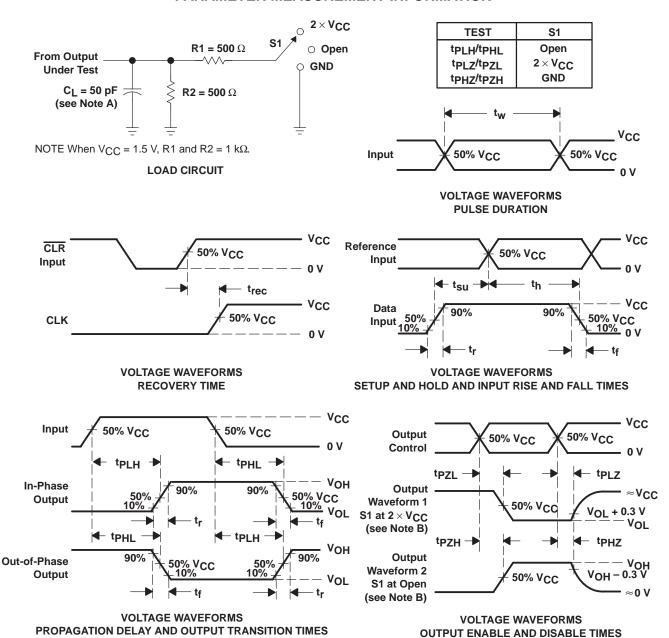
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	ТО	V	CD54AC163		CD74AC163		UNIT
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	MAX	MIN	MAX	UNIT
			1.5 V	7		8		
f _{max}			$3.3~\text{V}\pm0.3~\text{V}$	64		73		MHz
			5 V ± 0.5 V	90		103		
	CLK	RCO	1.5 V	_	209	_	190	
			$3.3~\text{V}\pm0.3~\text{V}$	6	23.4	6	21	
			5 V ± 0.5 V	4.3	16.7	4.3	15.2	
		Any Q	1.5 V	_	207	_	188	
t _{pd}			3.3 V ± 0.3 V	5.9	23.1	5.9	21	ns
			5 V ± 0.5 V	4.2	16.5	4.2	15	
			1.5 V	_	129	_	117	
	ENT	RCO	$3.3~\text{V}\pm0.3~\text{V}$	3.6	14.4	3.7	13.1	
			5 V ± 0.5 V	2.6	10.3	2.7	9.4	

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
pd Power	dissipation capacitance	No load	66	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \ \Omega$, $t_f = 3 \ ns$, $t_f = 3 \ ns$. Phase relationships between waveforms are arbitrary.
- D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLH and tpHL are the same as tpd.
- G. t_{PZL} and t_{PZH} are the same as t_{en} .
- H. t_{PLZ} and t_{PHZ} are the same as t_{dis} .

Figure 1. Load Circuit and Voltage Waveforms



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